

Multilayer Ceramic Chip Capacitors

C2012CH2E102K085AA



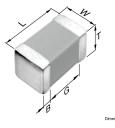






TDK item description C2012CH2E102KT****

Applications	Commercial Grade	
Feature	Mid Mid Voltage (100 to 630V)	
Series	C2012 [EIA 0805]	
Status	Production (Not Recommended for New Design)	



	Size
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	0.85mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
recommended Land Pattern (FA)	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
Neconinented Land Pattern (FB)	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
Neconiniended Land i accent (FC)	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	1nF ±10%	
Rated Voltage	250VDC	
Temperature Characteristic	CH(0±60ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Caldarina Mathad	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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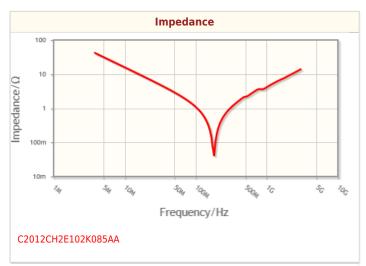




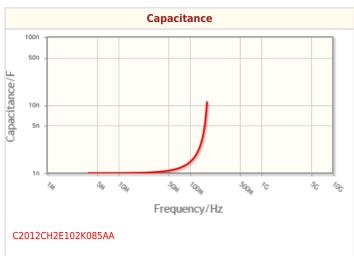


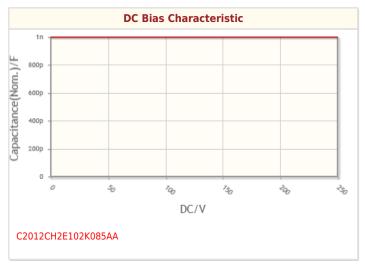


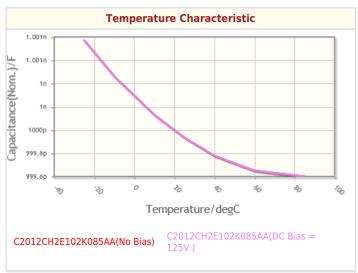
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)











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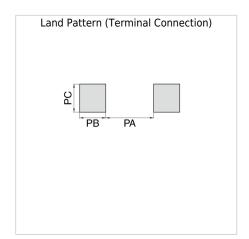








Associated Images



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